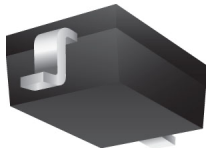


MATERIAL DECLARATION SHEET



Package Type	CDSOD323-TxxC			
Product Line	Semiconductor Products			
Compliance Date	April 27, 2023			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy Resin	0.002952	Amorphous Silica	60676-86-0	91.69	47.230	51.5180
				Epoxy Resin A	Proprietary	4.17	2.150	
				Epoxy Resin B	29690-82-2	1.41	0.728	
				Phenol Resin	Proprietary	2.15	1.110	
				Carbon Black	1333-86-4	0.58	0.300	
2	Leadframe	Copper Alloy	0.002045	Copper	7440-50-8	97.399	34.763	35.690
				Iron	7439-89-6	2.389	0.852	
				Phosphorus	7723-14-0	0.076	0.027	
				Zinc	7440-66-6	0.127	0.045	
				Lead	7439-92-1	0.009	0.003	
		Silver Plating	0.000029	Silver	7440-22-4	100.00	0.506	0.506
3	Chip	Silicon	0.00044	Silicon	7440-21-3	88.60	6.860	7.679
				Nickel	7440-02-0	5.93	0.460	
				Aluminum	7429-90-5	5.10	0.331	
				Gold	7440-57-5	0.37	0.028	
4	Die Attach	Silver Epoxy	0.000074	Silver	7440-22-4	95.19	1.229	1.291
				Bisphenol-F-(Epichlorhydrin); Epoxy resin	9003-36-5	2.76	0.035	
				1,4-Bis(2,3-epoxypropoxy) butane	2425-79-8	1.06	0.014	
				Aromatic polyamine	Proprietary	0.96	0.012	
				Adipic Acid	124-04-9	0.03	0.001	
5	Bond Wires	Copper	0.00002	Copper	7440-50-8	98.26	0.343	0.349
				Non - Cu element	Proprietary	1.74	0.006	
6	Lead Finish	Matte Tin	0.00017	Tin	7440-31-5	100.00	2.967	2.967
Total Weight			0.00573					

Important remarks:

1. It is responsibility of the user to verify they are accessing the latest version.